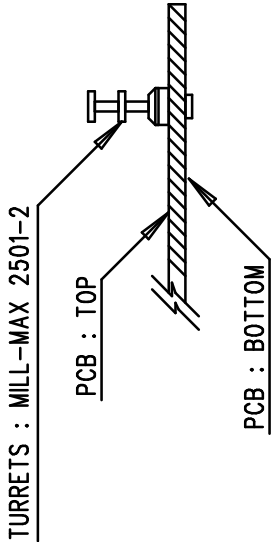
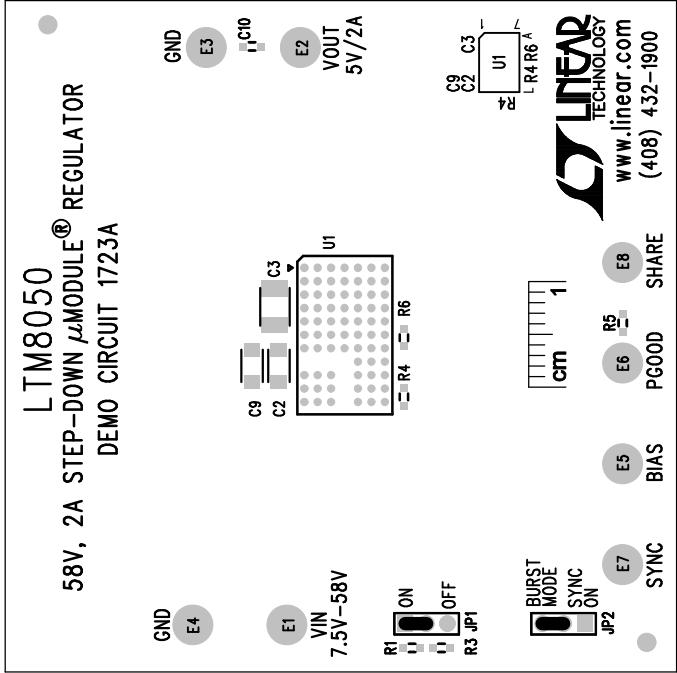


REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG. DATE
-	3	PRODUCTION	JAINO P. 03-12-13

NOTES: UNLESS OTHERWISE SPECIFIED

1. **MAXIMUM SOLDER TEMPERATURE IS 240 DEG C.**
2. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS.
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE
BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP
TO ANY BOARD.



APPROVALS		LINEAR TECHNOLOGY				1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL - FOR CUSTOMER USE ONLY	
PCB DES.	JW	TITLE: TOP ASSEMBLY DRAWING		58V, 2A STEP-DOWN μ MODULE [®] REGULATOR			
APP ENG.	JAINO P.						
SCALE = NONE		SIZE N/A	IC NO. LTM8050EY	REV. 3	DEMO CIRCUIT 1723A		
		FILENAME: 1723A-3.PCB		SHT 1 OF 2			